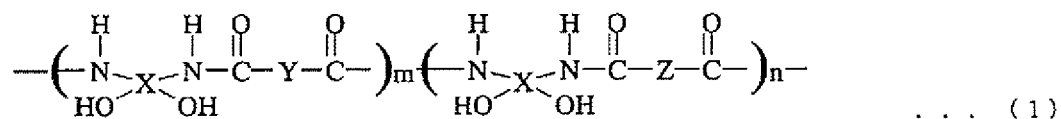


**Amendments to the Claims:**

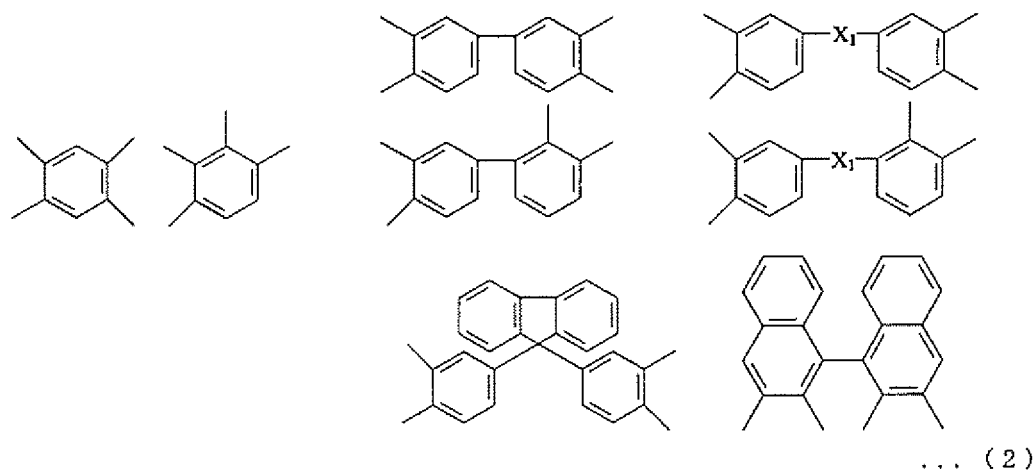
This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

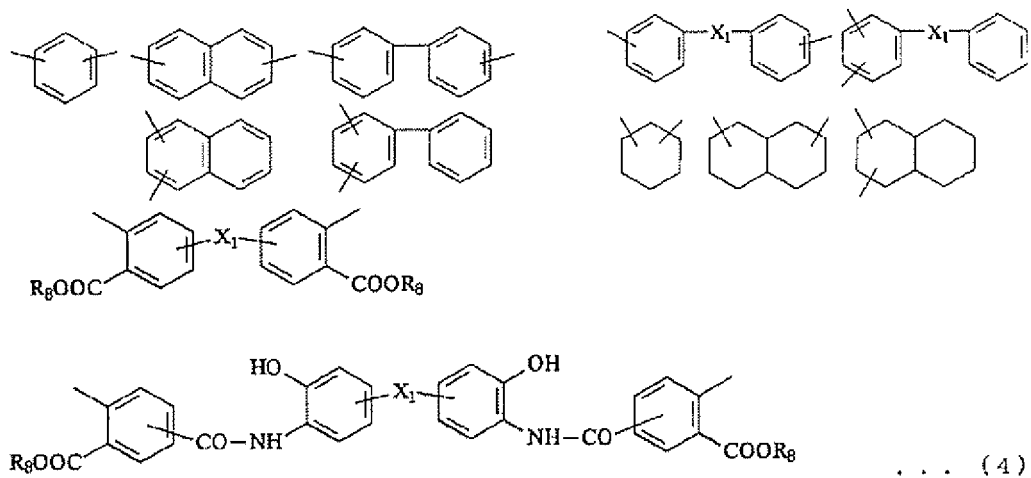
1. (Original) A hydroxypolyamide having a structure represented by the general formula (1):



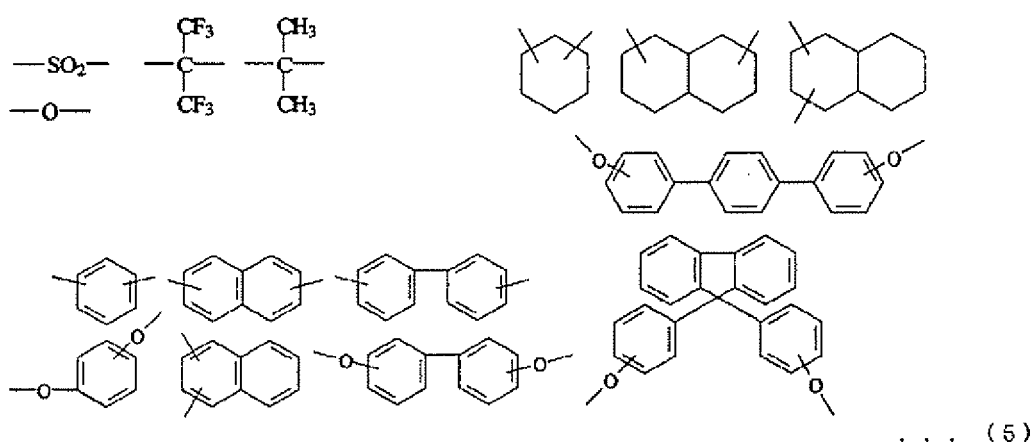
wherein m and n are integers satisfying  $m > 0$ ,  $n \geq 0$ ,  $2 \leq m+n \leq 1,000$ , and  $0.05 \leq m/(m+n) \leq 1$ , and the recurring units may be arranged blockwise or randomly; X represents at least one tetravalent organic group selected from groups represented by the following formula (2); Y represents 5-aminoisophthalic acid having at least one hydrogen atom of the amino group substituted, from which a carboxylic acid group is excluded; and Z represents at least one divalent group selected from groups represented by the following formula (4),



wherein  $X_1$  represents a divalent organic group selected from groups represented by the following formula (5); and the hydrogen atoms on each aromatic ring may be substituted with at least one group selected from the group consisting of a methyl group, an ethyl group, a propyl group, an isopropyl group, a butyl group, an isobutyl group, a t-butyl group, a fluorine atom, and a trifluoromethyl group,

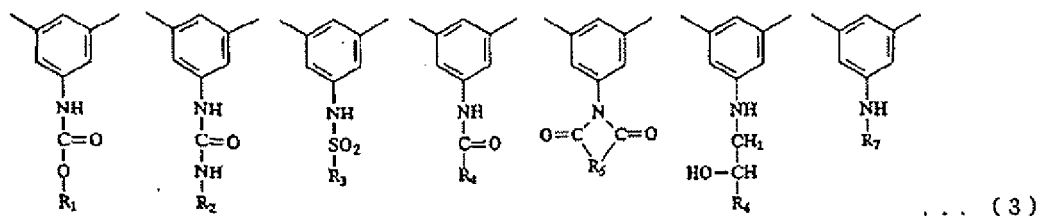


wherein  $R_8$  represents a monovalent organic group;  $X_1$  represents a divalent organic group selected from groups represented by the following formula (5); and the hydrogen atoms on each aromatic ring may be substituted with at least one group selected from the group consisting of a methyl group, an ethyl group, a propyl group, an isopropyl group, a butyl group, an isobutyl group, a t-butyl group, a fluorine atom, and a trifluoromethyl group, and



wherein the hydrogen atoms on each aromatic ring may be substituted with at least one group selected from the group consisting of a methyl group, an ethyl group, a propyl group, an isopropyl group, a butyl group, an isobutyl group, a t-butyl group, a fluorine atom, and a trifluoromethyl group.

2. (Original) The hydroxypolyamide according to claim 1 wherein Y represents at least one divalent organic group selected from groups represented by the following formula (3):



wherein  $R_1$ ,  $R_2$ ,  $R_3$ ,  $R_4$ , and  $R_6$  are each independently a monovalent organic group;  $R_5$  is a divalent organic group;  $R_7$  is at least one group selected from the group consisting of an aralkyl group, an arylsulfenyl group, a diarylphosphinyl group, and a tri-substituted silyl group; and the hydrogen atoms on each aromatic ring may be substituted with at least one group selected from the group consisting of a methyl group, an ethyl group, a propyl group, an isopropyl group, a butyl group, an isobutyl group, a t-butyl group, a fluorine atom, and a trifluoromethyl group.

3. (Currently Amended) A resin composition comprising 100 parts by mass of the hydroxypolyamide according to claim 1 or 2 (A) and 70 to 900 parts by mass of an organic solvent (D).

4. (Currently Amended) A resin composition comprising 100 parts by mass of the hydroxypolyamide according to claim 1 ~~or~~ 2 (A), 1 to 50 parts by mass of a crosslinking agent (B), and 70 to 900 parts by mass of an organic solvent (D).
5. (Currently Amended) A resin composition comprising 100 parts by mass of the hydroxypolyamide according to claim 1 ~~or~~ 2 (A), 1 to 100 parts by mass of an optically active compound with a naphthoquinonediazide group (C), and 70 to 900 parts by mass of an organic solvent (D), and having positive photosensitivity.
6. (Currently Amended) A resin composition comprising 100 parts by mass of the hydroxypolyamide according to claim 1 ~~or~~ 2 (A), 1 to 50 parts by mass of a crosslinking agent (B), 1 to 100 parts by mass of an optically active compound with a naphthoquinonediazide group (C), and 70 to 900 parts by mass of an organic solvent (D), and having positive photosensitivity.
7. (Currently Amended) The resin composition according to claim 4 ~~or~~ 6 wherein the crosslinking agent (B) is an acrylate compound.

8. (Currently Amended) The resin composition according to claim 4 ~~or 6~~ wherein the crosslinking agent (B) is an epoxy compound.

9. (Currently Amended) A process for producing a cured relief pattern, comprising the steps of: applying the resin composition according to claim 5 ~~or 6~~ onto a substrate; exposing the resultant coating film to an active light through a mask or directly irradiating the coating film with actinic rays; eluting and removing the part exposed or irradiated with the actinic rays using a developer; and heating the resultant positive relief pattern at 150 to 400°C.

10. (Original) A semiconductor device having a layer made of a cured relief pattern obtained by the production process according to claim 9.